

Mechanical Support System for a Thin Package

Abstract of the Disclosure

- 5 An electronic package includes an IC, such as a die, mounted onto one side of a thin interposer and a pin carrier mounted to an opposing side of the interposer. The pin carrier includes a cavity underneath the die. The cavity allows capacitors, or other electronic components, to be mounted against the interposer beneath the die. The cavity in the pin carrier is filled with an encapsulant to mechanically support the thin interposer in the area of the cavity during operation of an electronic
- 10 system that includes the package.

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